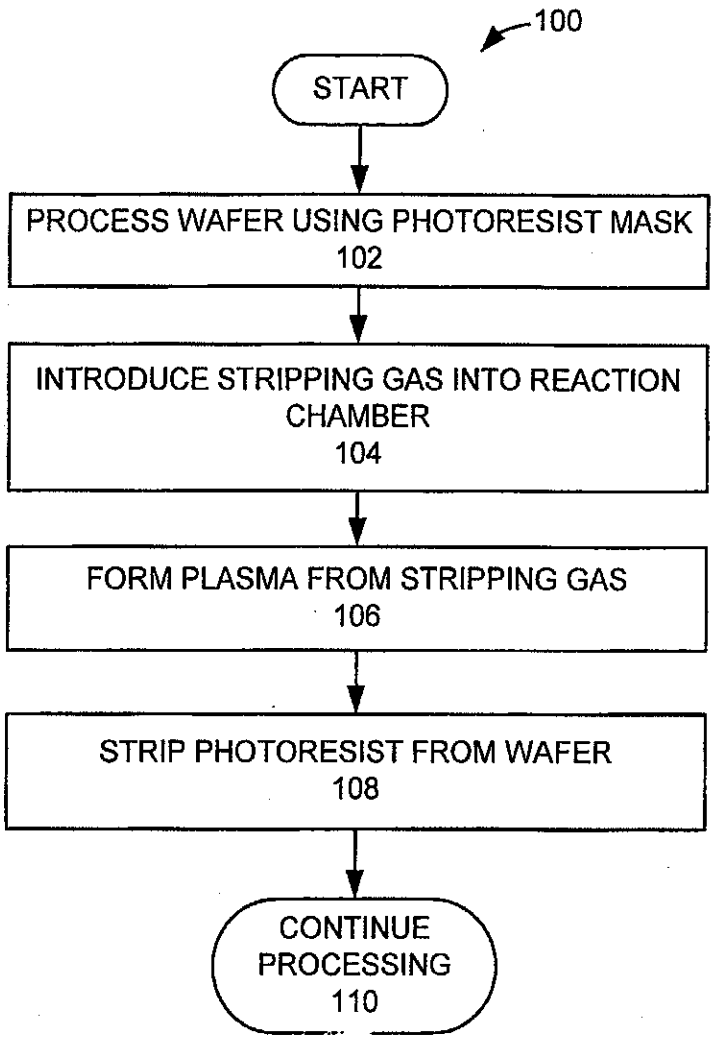

100
START
PROCESS WAFER USING PHOTORESIST MASK
102
INTRODUCE STRIPPING GAS INTO REACTION CHAMBER
104
FORM PLASMA FROM STRIPPING GAS
106
STRIP PHOTORESIST FROM WAFER
108
CONTINUE PROCESSING
110

FIG. 1

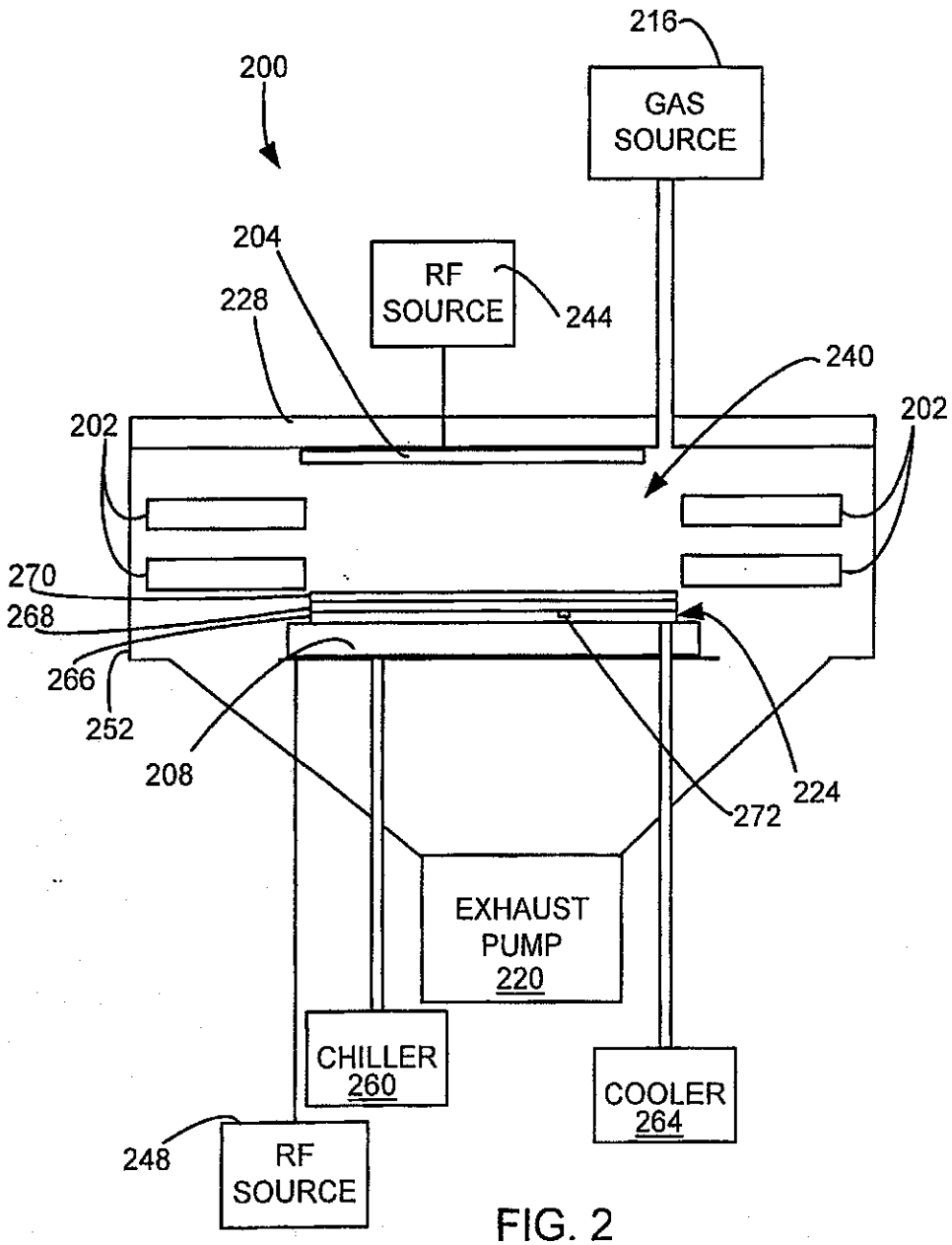

216
200
GAS SOURCE
204
RF SOURCE
244
228
240
202
202
270
268
266
252
208
224
272
EXHAUST PUMP 220
CHILLER 260
COOLER 264
248
RF SOURCE

FIG. 2